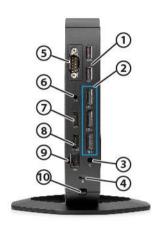
### **Overview**

### **HP t640 Thin Client**





- 1 Power button (with integrated power indicator)
- 2 Flash memory activity indicator
- 3 (1) USB-A 3.1 Gen 1 port
- 4 (1) USB-A 3.1 Gen 2 port
- 5 (1) USB-C™ 3.1 Gen 2 port
- 6 3.5 mm combo headset/audio jack
- 7 Access panel to information labels and VESA 100 mounting holes
- 8 System stand



### **BACK**

- 1 (2) USB-A 3.1 Gen 1 port
- 2 (3) DisplayPort ™1.2 digital video outputs
- 3 19V DC power input
- 4 Cable lock slot
- 5 Configurable Option Port supporting one of the following:
  - Blank; no optional configured port
  - 2 x USB-A 3.1 Gen 1 ports
  - DisplayPort<sup>™</sup> over USB-C<sup>™</sup> with USB Power Delivery
  - HDMI digital video output
  - VGA analog video output
  - External Wi-Fi antenna connector
  - Fiber Optic NIC connectors (SC or LC)
  - Serial port with configurable power (shown)
  - Dual serial ports (includes cable adapter)
- 6 3.5 mm audio jack
- 7 (1) USB-A 2.0 port
- 8 (1) USB-A 2.0 port (designated for *Power-on with Keyboard* if equipped)
- 9 RJ45 GbE network connector
- 10 Rear I/O cover removal latch



### **Overview**

### **AT A GLANCE**

- AMD Ryzen R1505G System-on-Chip; 2.4 3.3 GHz; 2 cores, 4 threads<sup>3</sup>
- AMD Memory Guard Secure Run technology that encrypts data in main memory
- DDR4 dual-channel SDRAM system memory; up to 2400 MT/s transfer rate; two SODIMM slots
- (3) DisplayPort 1.2 video outputs supporting up to UHD/4K (3840 x 2160 @ 60 Hz) resolutions **NOTE:** DisplayPort cables and displays sold separately.
- Solid-state flash memory storage; M.2 form factor modules; one slot
- Gigabit Ethernet (GbE) network connection; support for DASH out-of-band remote management
- Optional Allied Telesis M.2 Fiber Optic NICs; Fast Ethernet (100 Mb/s) or Gigabit (1,000 Mb/s)
- Optional Intel Wireless-AC 9260 Wi-Fi/Bluetooth® adapter including antennas integrated internally in the chassis

**NOTE:** Fiber optic and Wi-Fi NIC options cannot be supported together<sup>1</sup>

NOTE: Wireless features, performance and support may vary depending on environmental variables such placement, settings and firmware of your access points. Please contact your wireless vendor for support of your wireless environment

- Optional remote external Wi-Fi antenna system
- Option Port with a selection of available factory options (see detailed listing later in this document)
- Integrated PC speaker for basic audio playback; 3.5 mm combo headset/audio port on front and 3.5 mm audio port on rear that can be configured as line in or line out supporting headphones, external speaker systems, or microphone
- 45W non-PFC external power adapter
- Security features include a TCG certified TPM version 2.0 and a system UEFI (BIOS) designed to address NIST SP 800-147 BIOS protection guidelines and NIST SP800-155 BIOS integrity measurement guidelines. A cable lock slot is provided for use with a cable lock to enable the system's physical security
- Passive thermal design (no cooling fans) and active thermal management technology that monitors the system operating temperatures, throttles SOC operation if appropriate and prevents unit thermal shutdown.
- Rated for a maximum ambient operating temperature of 40 degree C
- ENERGY STAR® certified and EPEAT® Silver registered in the United States (except for some models configured with Fiber Optic NIC networking options). See http://www.epeat.net for registration status in other countries
- Post-consumer recycled plastics content greater than 25% total unit plastics (by weight)
- Low halogen<sup>2</sup> material content
- All models TAA compliant in North America

### Warranty

HP Customer Support: limited three-year hardware limited warranty in most regions; HP Care Packs are extended service contracts that go beyond your standard limited warranties; for more details visit <a href="http://www.hp.com/go/cpc">http://www.hp.com/go/cpc</a>



<sup>&</sup>lt;sup>1</sup> Wireless access point and Internet access is required; availability of public wireless access points is limited

<sup>&</sup>lt;sup>2</sup> This product is low halogen except for power cords, cables and peripherals, as well as the optional Fiber Optic NIC module; service parts obtained aftermarket may not be low halogen

<sup>&</sup>lt;sup>3</sup> Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed

## **Technical Specifications**

### **OPERATING SYSTEMS**

- HP ThinPro, including HP /Smart Zero Core
- Windows 10 IoT Enterprise LTSC 2019

### **PROCESSOR**

Model	CPU Frequency Max/Base	Cores/Threads	GPU Type	GPU Frequency
AMD Ryzen R1505G	3.3/2.4 GHz	2/4	Radeon Vega 3	1000 MHz

### **GRAPHICS**

Number of displays supported: 3

**Video outputs:** Standard: (3) DisplayPort™ 1.2

Optional: (1) DisplayPort™ over USB-C™ with USB Power Delivery

(1) VGA analog output(1) HDMI digital output

**NOTE:** adding and optional output does not increase the number of displays supported.

**Max. screen resolution:** 3840 x 2160 @ 60 Hz

NOTE: HP recommends dual channel memory (two SODIMMs) configurations for optimal display resolution performance

### **MEMORY**

Type: DDR4 dual channel SDRAM

Data Transfer Rate: Up to 2,400 MT/s

Peak Transfer Rate: Up to 19,200 MB/s

Number of Slots 2 x SODIMM

**Capacities:** 4, 8, 16 and 32 GB

#### **NOTES:**

- The actual transfer rates will be dependent upon the specification of the SODIMM modules used
- The Graphics Processing Unit (GPU) uses part of the total system memory. System memory dedicated to graphics performance is not available for use by other programs
- HP recommends dual channel memory (two SODIMMs) configurations for optimal system performance

### **Technical Specifications**

**UEFI** 

**UEFI Specification Revision** 

2.3.1

**TPM 2.0** 

Meets requirements for Common Criteria, an independent third-party certification of

trustworthiness

Meets requirements for FIPS 140-2, a standard for cryptographic integrity

**Security features** 

System UEFI designed to address NIST SP 800-147 BIOS protection guidelines and NIST SP800-155

BIOS integrity measurement guidelines

**STORAGE** 

**Type:** NAND flash memory; non-volatile

Number of Sockets: (1) M.2

Capacities: 16 GB M.2 eMMC flash module

32 GB M.2 eMMC flash module 64 GB M.2 eMMC flash module 128 GB M.2 SATA flash module 256 GB M.2 NVMe flash module 512 GB M.2 NVMe flash module

Input/Output

**Video Outputs:** 

USB:

Front access: (1) USB-A 3.1 Gen 1 port

(1) USB-A 3.1 Gen 2 port(1) USB-C™ 3.1 Gen 2 port

Rear access: (1) USB-A 2.0 port

(1) USB-A 2.0 port (designated for *Power-on from Keyboard* if equipped)

(2) USB-A 3.1 Gen 1 ports

(2) USB-A 3.1 Gen 1 ports (optional)(3) DisplayPort™ 1.2 digital outputs

Optional: (1) VGA analog output

Standard:

optional: (1) VGA analog output (1) HDMI digital output

(1) DisplayPort™ over USB-C™ with USB Power Delivery

**NOTE:** adding an optional output does not increase the number of displays supported.

I/O Interfaces: Standard: (1) RJ45 network connector

(1) 3.5 mm combo headset/audio jack (front)

(1) 3.5 mm audio jack (rear)

Optional: (1) serial port with configurable power

(2) serial ports enabled with an included cable adapter

**Option Port:** The rear I/O panel includes an Option Port that can be configured with one of the following factory

options:

• Blank; no optional configured port

2 x USB-A 3.1 Gen 1 ports

DisplayPort<sup>™</sup> over USB-C<sup>™</sup> with USB Power Delivery

HDMI digital video outputVGA analog video output

External Wi-Fi antenna connector (requires Wi-Fi adapter option)

Fiber Optic NIC connectors; SC or LC connector (requires Fiber Optic NIC option)

## **Technical Specifications**

- Serial port with configurable power
- Dual serial ports enabled with an included cable adapter

### **AUDIO/VIDEO**

**Audio Subsystem** 

- Internal amplified speaker system for basic audio playback
- 3.5 mm combo headset/headphone/analog microphone audio jack (front access)
- 3.5 mm combo line-out/ line-in socket (rear access)

**Audio CODECs** 

- MP3
- AAC Stereo
- HE AAC
- Includes hardware acceleration support

**Video CODECs** 

- MPEG-4 part 2 (DivX, Xvid)
- MPEG-4 part 10 (H.264, AVC), Advanced Video Coding (AVC) (H.264 encode)
- MPEG-H part 2, High Efficiency Video Coding (HEVC) (H.265 decode)
- WMV 7/8/9 VC-1 & ASF Demuxer
- Includes hardware acceleration support

### **NETWORKING**

**Local Area Networking** 

Realtek RTL8111EPH-CG Gigabit Ethernet (GbE) Controller with support for DASH out-of-band remote

management

**Wi-Fi Networking** 

Intel® Wireless-AC 9260 Wi-Fi/Bluetooth® combo; 2x2 802.11ac Wi-Fi and Bluetooth 5

**NOTES:** Wireless access point and internet access required. Availability of public wireless access points limited Wireless features, performance and support may vary depending on environmental variables such placement, settings and firmware of your access points. Please contact your wireless vendor for support of your wireless environment

### FIBER OPTIC NETWORKING

**Adapter Options:** 

- Allied Telesis AT-27M2/SC Fiber Fast Ethernet M.2 Adapter
- Allied Telesis AT-29M2/SC or LC Fiber Gigabit M.2 Adapter

**Features:** 

- IEEE 802.1p priority encoding/tagging (QoS, CoS)
- IEEE 802.1g VLAN tagging
- IEEE 802.3x flow control
- Buffer/FIFO: 2K transmit and 2K receive (AT-27M2)
- Buffer/FIFO: 22K transmit and 40K receive (AT-29M2)
- Loopback mode
- Descriptor-Based Buffer Management
- Wake-on-LAN from S3 (Sleep) and S4 (Hibernate) not supported
- Link Detection and PHY interface power; the PHY interface, Link detection and Link LED should be enabled by default at power-up

## **Technical Specifications**

Performance:

AT-27M2

- >= 85 Mbit/s receive, <= 30% CPU utilization
- >= 85 Mbit/s transmit, <= 30% CPU utilization
- >= 170 Mbit/s total bi-directional, <= 30% CPU utilization

**NOTE:** The minimum transfer size at 100 Mbit/s is 1 Gbps

AT-29M2

- >= 800 Mbit/s receive, <= 30% CPU utilization
- >= 800 Mbit/s transmit, <= 30% CPU utilization
- >= 1500 Mbit/s total bi-directional, <= 30% C:U utilization

**NOTE:** The minimum transfer size at 1000 Mbit/s is 1500 Gbps

External Interface: Complies with IEEE 802.3 1000BASE-X operation

Power:

- Uses less than 1775 mW of power at full performance (AT-27M2)
- Uses less than 2100 mW of power at full performance (AT-29M2)
- Supports all PCI Express bus states LO, LOs, L1 and L2

Non-volatile Storage:

The MAC address is unique for each system; assigned from the board assembly manufacturer's IEEE registered allocation.

The PCI subsystem ID is unique to HP and unique to each design to allow Windows Update to be finely controlled.



## **Technical Specifications**

## **SOFTWARE SUPPORT**

Heat Environment	Protocol	НР	Microsoft
Host Environment		ThinPro	Windows 10 IoT Enterprise 2019
Remote Desktop Services	Remote FX (RFX), RDP	✓	✓
Citrix®	ICA, HDX	✓	✓
VMware® Horizon	RDP, PCoIP, Blast Extreme	<b>~</b>	✓

Ductoral Clients	НР	Microsoft
Protocol Clients	ThinPro	Windows 10 IoT Enterprise 2019
Citrix® Workspace app	<b>✓</b>	✓
Microsoft Remote Desktop Client		✓
Free Remote Desktop Client	✓	
VMware™ Horizon View™ Client	✓	✓
HP Remote Graphics Software (RGS)	via add-on	✓
Turbosoft TTerm for Linux® Terminal emulation Software	via add-on	
Turbosoft TTWin Terminal emulation software		via add-on

Province Current	НР	Microsoft
Browser Support	ThinPro	Windows 10 IoT Enterprise 2019
Mozilla Firefox	✓	
Internet Explorer		✓

<b>6</b>	HP	Microsoft
Security	ThinPro	Windows 10 IoT Enterprise 2019
Smart Card	✓	✓
Log-on Manager	✓	✓
Read only Operating System	✓	✓
802.1x	✓	✓
Microsoft Firewall		✓
HP Write Manager		<b>✓</b>



Microsoft SCCM/EDM agent

**HP USB Port Manager** 

## **Technical Specifications**

Microsoft Unified Write Filter		<b>&gt;</b>
<b>NOTE:</b> the HP Write Manager is the default active we enabled by the user if required.	vrite filter. The Microsoft Unific	ed Write Filter is disabled by default but can be

HP Microsoft
ThinPro Windows 10 IoT Enterprise 2019

HP Device Manager

HP ThinUpdate

HP Easy Tools

HP Smart Zero Client Services

HP Smart Zero Client Services

Addisional Injudence Companyons	НР	Microsoft
Additional Windows Components	ThinPro	Windows 10 IoT Enterprise 2019
HP Easy Shell		<b>✓</b>
Windows Media Player		✓
Microsoft Direct Access		<b>✓</b>
Microsoft BranchCache		✓
Microsoft AppLocker		✓
Microsoft Sideloading		<b>✓</b>
CyberLink		<b>✓</b>

**NOTE:** Other add-on software available (see: http://www.hp.com/support for latest list of available add-ons). Software performance and support may vary depending on customer environment and backend.

Andia finida a CODEC-	НР	Microsoft
Audio/Video CODECs	ThinPro	Windows 10 IoT Enterprise 2019
MP3	~	✓
WMA stereo	~	✓
AAC stereo & HE AAC	✓	
Microsoft AC3 encoder		✓
MPEG-1	<b>✓</b>	



## **Technical Specifications**

MPEG-4 part 2 (DivX, Xvid, H.263)	<b>~</b>	<b>*</b>
MPEG-4 part 10 (H.264, AVC)	<b>✓</b>	<b>~</b>
WMV 7/8/9/ VC-1 & ASF Demuxer	<b>~</b>	<b>~</b>

### **WEIGHTS & DIMENSIONS**

WxDxH:

35 x 196 x 196 mm

Volume:

(vertical orientation)

1.34 liter

**System Weight** 

994.5g

(unit with stand)

**Shipping Weight** 

2878g

NOTE: All measurements are approximate; the addition of optional modules will increase the weight

### **EXTERNAL POWER SUPPLY**

45W non-PFC Smart external power adapter

Worldwide auto-sensing 100 - 240 VAC; nominal voltage is 120 VAC; 50 - 60 Hz

Entergy saving automatic power-down; surge tolerant

1.8m output cable

External power adapters are sourced from several suppliers in order to ensure adequate supply and availability is maintained. The actual dimensions of the power brick will vary by supplier.

HP P/N Vendor **Dimensions:** L25296-001 Lite-On 94 x 40 x 26.5 mm L25296-002 Chicony 95 x 40 x 26.5 mm Delta L25296-003 94 x 39 x 26.5 mm L25296-004 AcBel 91.4 x 44 x 26.8 mm



## **Technical Specifications**

### COMPLIANCE/CERTIFICATIONS

**Accessibility:** Section 508 Accessibility; VPAT report available.

**Environmental Stewardship:** Worldwide (ENERGY STAR®, EPEAT 2.0, RoHS2, ERP, TCO, CECP& SEPA, HP GSE, WEEE,

Low Halogen, etc.)

**Product Safety:** Worldwide (UL, CB, GS, CCC, BSMI, etc.)

**Electromagnetic Compliance (EMC):** Worldwide (FCC/CISPR/EN/VCCI/ICES/AS/NZS/CNS/KCC) "Class B" EMI regulations

**International Medical Safety Standard:** EN60601-1-2 (Medical Equipment EMC)

### **ENVIRONMENTAL**

Operating Temperature Range: 50° to 104° F 10° to 40° C Non-operating Temperature -22° to 140° F Range: -30° to 60° C

Humidity: Condensing: 20% to 80% Non-condensing: 10% to 90%

**NOTE:** Specifications are at sea level with altitude derating of 1° C/300m (1.8° F/1000ft) to a maximum of 3 Km (10,000 ft), with no direct, sustained sunlight. Upper limit may be limited by the type and number of options installed.

### Basic Configuration (does not include a fiber optic NIC):

Energy Consumption (in accordance with US ENERGY STAR® test method)	115 V ac, 60 Hz	230 V ac, 50 Hz	100 V ac, 60 Hz
Normal Operation (Short idle)	9.35 W	9.62 W	9.43 W
Normal Operation (Long idle)	8.45 W	8.62 W	8.52 W
Sleep	1.87 W	1.88 W	1.88 W
Off	1.85 W	1.71 W	1.71 W

Heat Dissipation*	115 V ac, 60 Hz	230 V ac, 50 Hz	100 V ac, 60 Hz
Normal Operation (Short idle)	32 BTU/hr	33 BTU/hr	32 BTU/hr
Normal Operation (Long idle)	29 BTU/hr	29 BTU/hr	29 BTU/hr
Sleep	6 BTU/hr	6 BTU/hr	6 BTU/hr
Off	6 BTU/hr	6 BTU/hr	6 BTU/hr

**NOTE:**Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

System configuration includes: HP Thin Pro 64bit operating system, 128 GB storage, 32 GB system memory, USB keyboard & mouse

### Optional Configuration (includes a fiber optic NIC):

Energy Consumption		
(in accordance with US ENERGY STAR® test	115 V ac, 60 Hz	230 V ac, 50 Hz
method)		

Normal Operation (Short idle) 10.9 W 11.19 W 11.13 W



100 V ac, 60 Hz

Technical Specifications							
Normal Operation (Long idle)	9.55 W	10.35 W	10.09 W				
Sleep	2.99 W	2.98 W	3.02 W				
Off	2.84 W	2.81 W	2.85 W				
Heat Dissipation*	115 V ac, 60 Hz	230 V ac, 50 Hz	100 V ac, 60 Hz				
Normal Operation (Short idle)	37 BTU/hr	38 BTU/hr	38 BTU/hr				
Normal Operation (Long idle)	33 BTU/hr	35 BTU/hr	34 BTU/hr				
Sleep	10 BTU/hr	10 BTU/hr	10 BTU/hr				
Off	10 BTU/hr	10 BTU/hr	10 BTU/hr				
NOTE: Heat discinction is calculated bea		de a ale a casa da a faccal de agradad	al familiar leaves				

**NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

System configuration includes: Windows 10 IoT Enterprise LTSC 2019 operating system, 128 GB storage, 32 GB system memory, 100 Mbps SC Fiber Optic NIC, USB keyboard & mouse

Acoustic Noise Emission D								
Measurement and	ISO 7779: Acoustics – Measurement of airborne noise emitted by information technology and							
declaration standards:	telecommunications equipment							
	ISO 9296: Acoustics – Declared noise emission values of computer and business equipment							
<b>Declared Noise Emission N</b>	/alues in acco	ordance with ISO 92	96					
Product Configuration or Operating Mode #	Declared Sound Power Level, Lwad Bels			Declared Sound Pressure Level, LpAm dBA				
				Tested on ISO Table				
	Idle	Operating		Idle	Operating			
(see section below for	ECMA-74	ECMA-74	ECMA-74	ECMA-74	ECMA-74	ECMA-74		
description)	C.15.3.2	C.9.3.2	C.15.3.3 g	C.15.3.2	C.9.3.2	C.15.3.3 g		
	Idle Mode	Drive Random Seek	Active Mode	Idle Mode	Drive Random Seek	Active Mode		
Vertical	2.5	2.5	2.5	13.7	13.7	13.7		
Horizontal	2.5	2.5	2.5	N/A	N/A	N/A		
				TCO				
					Blue Angel			
The Product meets the acoustic noise limits of these voluntary Eco labels:				Nordic Swan				
				EU Flower				
NOTE: Measured under IS	0 7770 and IS	O 0206 moscuromo	nt and doclaration					



## Summary of Changes

Date of change:	Version History:	Type of change	Description of change:
September 10, 2019	From v1 to v2	Added	Acoustic Noise Emission Declaration section
		_	Format page 2, changed Graphics, Memory, UEFI, WEIGHTS & DIMENSIONS and ENVIRONMENTAL sections



© 2019 HP Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products and services are set forth in the express limited warranty statements accompanying such products and services. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein. AMD and Radeon are trademarks of Advanced Micro Devices, Inc. DisplayPort™ and the DisplayPort™ logo are trademarks owned by the Video Electronics Standards Association (VESA®) in the United States and other countries. Amazon Web Services, the "Powered by Amazon Web Services" logo, and Amazon WorkSpaces are trademarks of Amazon.com, Inc. or its affiliates in the United States and/or other countries. Bluetooth® is a trademark owned by its proprietor and used by HP Inc. under license. ENERGY STAR is a registered trademark owned by the U.S. Environmental Protection Agency. Linux® is the registered trademark of Linus Torvalds in the U.S. and other countries. Microsoft and Windows are either registered trademarks or trademarks of Microsoft Corporation in the United States and/or other countries. Intel® is a trademark of Intel Corporation in the U.S and other countries. VMware Horizon and VMware Horizon View are registered trademarks of trademarks of VMware, Inc. in the United States and/or other jurisdictions. Citrix and Citrix Workspace are trademark Office and in other countries.

